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MacDermid Alpha Releases Systek UVF 100: 2 in 1 RDL Simultaneous Copper Via Filling and Fine Line Plating for IC Substrate Manufacturing

(Waterbury, CT USA) – July 8th, 2020 – MacDermid Alpha Electronics Solutions, a global leader in specialty materials for electronics, announces the release of Systek UVF 100, the newest release in the Systek family of IC Substrate manufacturing solutions.

Systek UVF 100 is a high performance 2 in 1 plating system for the build-up of redistribution layers (RDL). The Systek UVF 100 is a pattern plating process capable of filling blind micro vias and laser drilled X-vias as well as plating fine lines, pads, and other surface features with a high degree of coplanarity and controlled profile. RDL blind micro vias and X-vias can be reliably filled with dimples of less than 5µm and overfill of less than 3µm eliminating dielectric layer thinning concerns while providing an excellent base for further build up. Systek UVF 100 plates surface features with excellent coplanarity, with measured R-values well below 2µm. The trace profile of the traces plated are consistently less than 15% for highly controlled impedance. Process quality is ensured with CVS analysis and control of all additives.

The Systek UVF 100 can be used in combination with the Systek Semi-Additive (SAP) and Embedded Trace (ETS) technologies to meet the finest line and space requirements of today's IC substrate designs.

“The excellent coplanarity, trace profile, and via filling performance of the Systek UVF 100 is the result of our expertise in additive synthesis in the advanced PCB and semiconductor spaces that enable a new era of organic substrate designs. The Systek UVF 100 process provides manufacturers of advanced IC substrates with a reliable panel-level packaging solution that meets advanced design requirements.” – Rich Bellemare, Director of Electrolytic Metallization, Circuitry Solutions.

For more information on Systek UVF 100, please visit www.MacDermidAlpha.com

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